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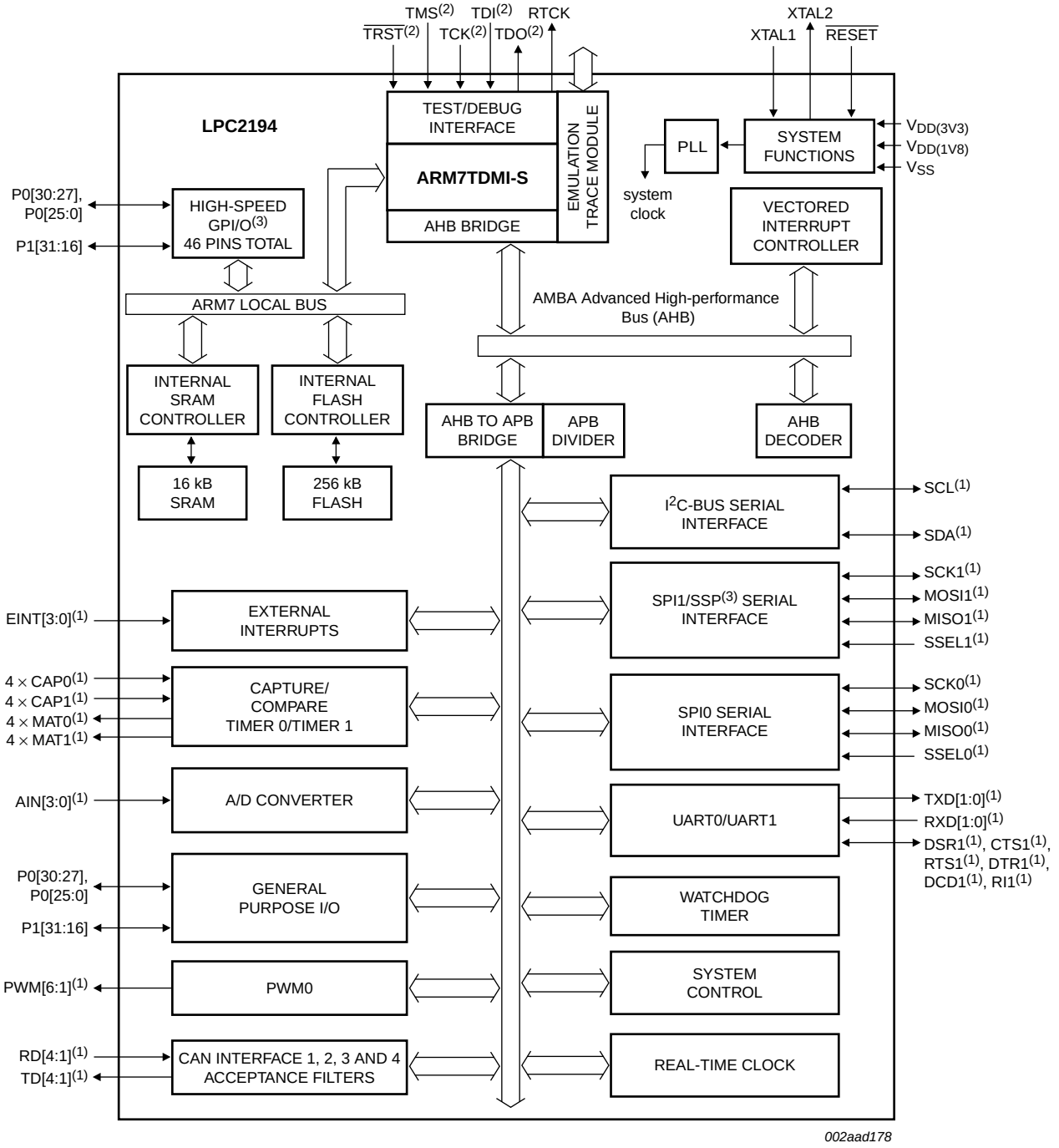
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	60MHz
Connectivity	CANbus, I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	46
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc2194hbd64-01-15

4. Block diagram



(1) Shared with GPIO.

(2) When test/debug interface is used, GPIO/other functions sharing these pins are not available.

(3) SSP interface and high-speed GPIO are available on LPC2194/01 only.

Fig 1. Block diagram

Table 2. Pin description *…continued*

Symbol	Pin	Type	Description
P0[30]/AIN3/ EINT3/CAP0[0]	15	I	**AIN3 —** A/D converter, input 3. This analog input is always connected to its pin.
		I	**EINT3 —** External interrupt 3 input.
		I	**CAP0[0] —** Capture input for Timer 0, channel 0.
P1[0] to P1[31]		I/O	Port 1 is a 32-bit bidirectional I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the Pin Connect Block. Pins 0 through 15 of port 1 are not available.
P1[16]/ TRACEPKT0	16	O	Trace Packet, bit 0. Standard I/O port with internal pull-up.
P1[17]/ TRACEPKT1	12	O	Trace Packet, bit 1. Standard I/O port with internal pull-up.
P1[18]/ TRACEPKT2	8	O	Trace Packet, bit 2. Standard I/O port with internal pull-up.
P1[19]/ TRACEPKT3	4	O	Trace Packet, bit 3. Standard I/O port with internal pull-up.
P1[20]/ TRACESYNC	48	O	Trace Synchronization. Standard I/O port with internal pull-up. **Note:** LOW on this pin while $\overline{\text{RESET}}$ is LOW, enables pins P1[25:16] to operate as Trace port after reset.
P1[21]/ PIPESTAT0	44	O	Pipeline Status, bit 0. Standard I/O port with internal pull-up.
P1[22]/ PIPESTAT1	40	O	Pipeline Status, bit 1. Standard I/O port with internal pull-up.
P1[23]/ PIPESTAT2	36	O	Pipeline Status, bit 2. Standard I/O port with internal pull-up.
P1[24]/ TRACECLK	32	O	Trace Clock. Standard I/O port with internal pull-up.
P1[25]/EXTIN0	28	I	External Trigger Input. Standard I/O with internal pull-up.
P1[26]/RTCK	24	I/O	Returned Test Clock output. Extra signal added to the JTAG port. Assists debugger synchronization when processor frequency varies. Bidirectional pin with internal pull-up. **Note:** LOW on this pin while $\overline{\text{RESET}}$ is LOW, enables pins P1[31:26] to operate as Debug port after reset.
P1[27]/TDO	64	O	Test Data out for JTAG interface.
P1[28]/TDI	60	I	Test Data in for JTAG interface.
P1[29]/TCK	56	I	Test Clock for JTAG interface. This clock must be slower than $\frac{1}{6}$ of the CPU clock (CCLK) for the JTAG interface to operate.
P1[30]/TMS	52	I	Test Mode Select for JTAG interface.
P1[31]/$\overline{\text{TRST}}$	20	I	Test Reset for JTAG interface.
TD1	10	O	CAN1 transmitter output.
$\overline{\text{RESET}}$	57	I	external reset input; a LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. TTL with hysteresis, 5 V tolerant.
XTAL1	62	I	input to the oscillator circuit and internal clock generator circuits.
XTAL2	61	O	output from the oscillator amplifier.
V_{SS}	6, 18, 25, 42, 50	I	ground: 0 V reference.

Table 2. Pin description *…continued*

Symbol	Pin	Type	Description
V_{SSA}	59	I	analog ground; 0 V reference. This should nominally be the same voltage as V_{SS}, but should be isolated to minimize noise and error.
$V_{SSA(PLL)}$	58	I	PLL analog ground; 0 V reference. This should nominally be the same voltage as V_{SS}, but should be isolated to minimize noise and error.
$V_{DD(1V8)}$	17, 49	I	1.8 V core power supply; this is the power supply voltage for internal circuitry.
$V_{DDA(1V8)}$	63	I	analog 1.8 V core power supply; this is the power supply voltage for internal circuitry. This should be nominally the same voltage as $V_{DD(1V8)}$ but should be isolated to minimize noise and error.
$V_{DD(3V3)}$	23, 43, 51	I	3.3 V pad power supply; this is the power supply voltage for the I/O ports.
$V_{DDA(3V3)}$	7	I	analog 3.3 V pad power supply; this should be nominally the same voltage as $V_{DD(3V3)}$ but should be isolated to minimize noise and error.

[1] SSP interface available on LPC2194/01 only.

6. Functional description

Details of the LPC2194 systems and peripheral functions are described in the following sections.

6.1 Architectural overview

The ARM7TDMI-S is a general purpose 32-bit microprocessor, which offers high performance and very low power consumption. The ARM architecture is based on Reduced Instruction Set Computer (RISC) principles, and the instruction set and related decode mechanism are much simpler than those of microprogrammed Complex Instruction Set Computers. This simplicity results in a high instruction throughput and impressive real-time interrupt response from a small and cost-effective processor core.

Pipeline techniques are employed so that all parts of the processing and memory systems can operate continuously. Typically, while one instruction is being executed, its successor is being decoded, and a third instruction is being fetched from memory.

The ARM7TDMI-S processor also employs a unique architectural strategy known as Thumb, which makes it ideally suited to high-volume applications with memory restrictions, or applications where code density is an issue.

The key idea behind Thumb is that of a super-reduced instruction set. Essentially, the ARM7TDMI-S processor has two instruction sets:

- The standard 32-bit ARM set.
- A 16-bit Thumb set.

The Thumb set's 16-bit instruction length allows it to approach twice the density of standard ARM code while retaining most of the ARM's performance advantage over a traditional 16-bit processor using 16-bit registers. This is possible because Thumb code operates on the same 32-bit register set as ARM code.

Thumb code is able to provide up to 65 % of the code size of ARM, and 160 % of the performance of an equivalent ARM processor connected to a 16-bit memory system.

6.2 On-chip flash program memory

The LPC2194 incorporates a 256 kB flash memory system. This memory may be used for both code and data storage. Programming of the flash memory may be accomplished in several ways. It may be programmed In System via the serial port. The application program may also erase and/or program the flash while the application is running, allowing a great degree of flexibility for data storage field firmware upgrades, etc. When on-chip bootloader is used, 248 kB of flash memory is available for user code.

The LPC2194 flash memory provides a minimum of 100000 erase/write cycles and 20 years of data retention.

On-chip bootloader (as of revision 1.60) provides Code Read Protection (CRP) for the LPC2194 on-chip flash memory. When the CRP is enabled, the JTAG debug port and ISP commands accessing either the on-chip RAM or flash memory are disabled. However, the

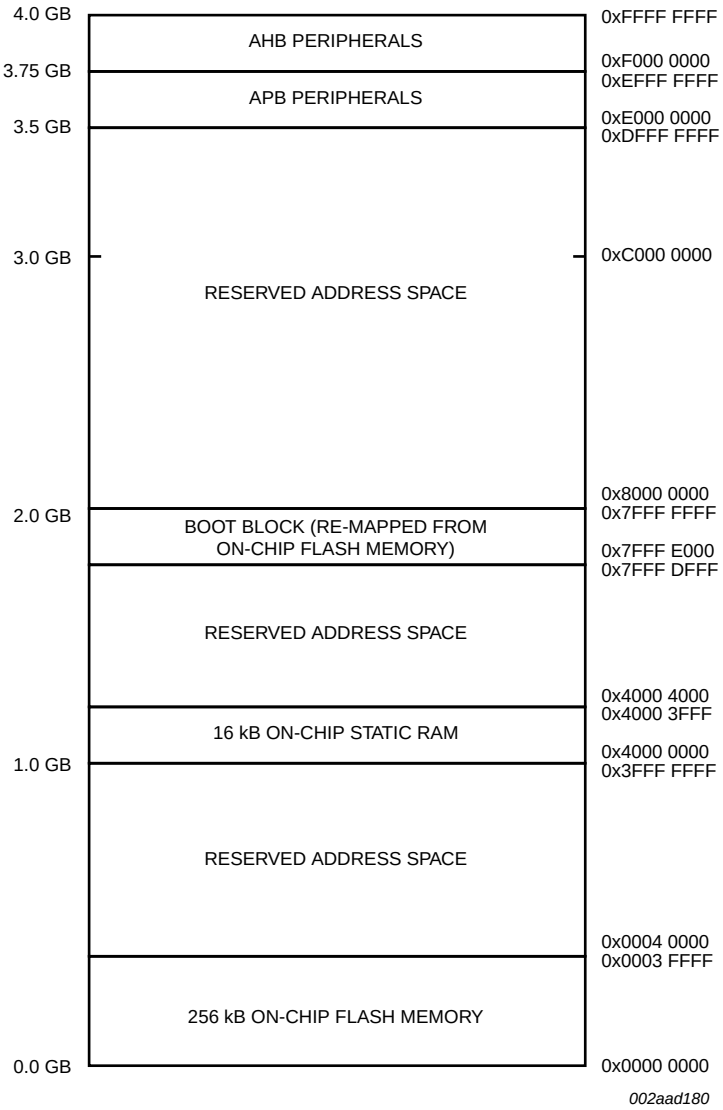


Fig 3. LPC2194 memory map

6.5 Interrupt controller

The Vectored Interrupt Controller (VIC) accepts all of the interrupt request inputs and categorizes them as Fast Interrupt Request (FIQ), vectored Interrupt Request (IRQ), and non-vectored IRQ as defined by programmable settings. The programmable assignment scheme means that priorities of interrupts from the various peripherals can be dynamically assigned and adjusted.

FIQ has the highest priority. If more than one request is assigned to FIQ, the VIC combines the requests to produce the FIQ signal to the ARM processor. The fastest possible FIQ latency is achieved when only one request is classified as FIQ, because then the FIQ service routine can simply start dealing with that device. But if more than one request is assigned to the FIQ class, the FIQ service routine can read a word from the VIC that identifies which FIQ source(s) is (are) requesting an interrupt.

- Ports are accessible via either the legacy group of registers (GPIOs) or the group of registers providing accelerated port access (Fast GPIOs).

6.8 10-bit ADC

The LPC2194 each contain a single 10-bit successive approximation ADC with four multiplexed channels.

6.8.1 Features

- Measurement range of 0 V to 3 V.
- Capable of performing more than 400000 10-bit samples per second.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition on input pin or Timer Match signal.

6.8.2 ADC features available in LPC2194/01 only

- Every analog input has a dedicated result register to reduce interrupt overhead.
- Every analog input can generate an interrupt once the conversion is completed.
- The ADC pads are 5 V tolerant when configured for digital I/O function(s).

6.9 CAN controllers and acceptance filter

The LPC2194 contains four CAN controllers. The CAN is a serial communications protocol which efficiently supports distributed real-time control with a very high level of security. Its domain of application ranges from high-speed networks to low-cost multiplex wiring.

6.9.1 Features

- Data rates up to 1 Mbit/s on each bus.
- 32-bit register and RAM access.
- Compatible with CAN specification 2.0B, ISO 11898-1.
- Global Acceptance Filter recognizes 11-bit and 29-bit Rx identifiers for all CAN buses.
- Acceptance Filter can provide FullCAN-style automatic reception for selected Standard identifiers.

6.10 UARTs

The LPC2194 each contain two UARTs. In addition to standard transmit and receive data lines, the UART1 also provides a full modem control handshake interface.

6.10.1 Features

- 16 B Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.

6.12 SPI serial I/O controller

The LPC2194 each contain two SPIs. The SPI is a full duplex serial interface, designed to be able to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends a byte of data to the slave, and the slave always sends a byte of data to the master.

6.12.1 Features

- Compliant with Serial Peripheral Interface (SPI) specification.
- Synchronous, Serial, Full Duplex communication.
- Combined SPI master and slave.
- Maximum data bit rate of $1/8$ of the input clock rate.

6.12.2 Features available in LPC2194/01 only

- Eight to 16 bits per frame.
- When the SPI interface is used in Master mode, the SSELn pin is not needed (can be used for a different function).

6.13 SSP controller (LPC2194/01 only)

The SSP is a controller capable of operation on a SPI, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. Data transfers are in principle full duplex, with frames of four to 16 bits of data flowing from the master to the slave and from the slave to the master.

While the SSP and SPI1 peripherals share the same physical pins, it is not possible to have both of these two peripherals active at the same time. The application can switch on the fly from SPI1 to SSP and back.

6.13.1 Features

- Compatible with Motorola's SPI, Texas Instrument's 4-wire SSI, and National Semiconductor's Microwire buses.
- Synchronous serial communication.
- Master or slave operation.
- 8-frame FIFOs for both transmit and receive.
- Four to 16 bits per frame.

6.14 General purpose timers

The Timer/Counter is designed to count cycles of the peripheral clock (PCLK) or an externally supplied clock and optionally generate interrupts or perform other actions at specified timer values, based on four match registers. It also includes four capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt. Multiple pins can be selected to perform a single capture or match function, providing an application with 'or' and 'and', as well as 'broadcast' functions among them.

6.14.1 Features

- A 32-bit Timer/Counter with a programmable 32-bit Prescaler.
- Timer or external event counter operation
- Four 32-bit capture channels per timer that can take a snapshot of the timer value when an input signal transitions. A capture event may also optionally generate an interrupt.
- Four 32-bit match registers that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Four external outputs per timer corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.

6.14.2 Features available in LPC2194/01 only

The LPC2194/01 can count external events on one of the capture inputs if the external pulse lasts at least one half of the period of the PCLK. In this configuration, unused capture lines can be selected as regular timer capture inputs, or used as external interrupts.

- Timer can count cycles of either the peripheral clock (PCLK) or an externally supplied clock.
- When counting cycles of an externally supplied clock, only one of the timer's capture inputs can be selected as the timer's clock. The rate of such a clock is limited to PCLK / 4. Duration of HIGH/LOW levels on the selected CAP input cannot be shorter than 1 / (2PCLK).

6.15 Watchdog timer

The purpose of the watchdog is to reset the microcontroller within a reasonable amount of time if it enters an erroneous state. When enabled, the watchdog will generate a system reset if the user program fails to 'feed' (or reload) the watchdog within a predetermined amount of time.

6.15.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect/incomplete feed sequence causes reset/interrupt if enabled.

With double edge controlled PWM outputs, specific match registers control the rising and falling edge of the output. This allows both positive going PWM pulses (when the rising edge occurs prior to the falling edge), and negative going PWM pulses (when the falling edge occurs prior to the rising edge).

6.17.1 Features

- Seven match registers allow up to six single edge controlled or three double edge controlled PWM outputs, or a mix of both types.
- The match registers also allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Supports single edge controlled and/or double edge controlled PWM outputs. Single edge controlled PWM outputs all go HIGH at the beginning of each cycle unless the output is a constant LOW. Double edge controlled PWM outputs can have either edge occur at any position within a cycle. This allows for both positive going and negative going pulses.
- Pulse period and width can be any number of timer counts. This allows complete flexibility in the trade-off between resolution and repetition rate. All PWM outputs will occur at the same repetition rate.
- Double edge controlled PWM outputs can be programmed to be either positive going or negative going pulses.
- Match register updates are synchronized with pulse outputs to prevent generation of erroneous pulses. Software must ‘release’ new match values before they can become effective.
- May be used as a standard timer if the PWM mode is not enabled.
- A 32-bit Timer/Counter with a programmable 32-bit Prescaler.

6.18 System control

6.18.1 Crystal oscillator

The oscillator supports crystals in the range of 1 MHz to 30 MHz. The oscillator output frequency is called f_{osc} and the ARM processor clock frequency is referred to as CCLK for purposes of rate equations, etc. f_{osc} and CCLK are the same value unless the PLL is running and connected. Refer to Section 6.18.2 “PLL” for additional information.

6.18.2 PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up into the range of 10 MHz to 60 MHz with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32 (in practice, the multiplier value cannot be higher than 6 on this family of microcontrollers due to the upper frequency limit of the CPU). The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider may be set to divide

by 2, 4, 8, or 16 to produce the output clock. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip Reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to Lock, then connect to the PLL as a clock source. The PLL settling time is 100 μs.

6.18.3 Reset and wake-up timer

Reset has two sources on the LPC2194: the $\overline{\text{RESET}}$ pin and Watchdog Reset. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin with an additional glitch filter. Assertion of chip Reset by any source starts the Wake-up Timer (see Wake-up Timer description below), causing the internal chip reset to remain asserted until the external Reset is de-asserted, the oscillator is running, a fixed number of clocks have passed, and the on-chip flash controller has completed its initialization.

When the internal Reset is removed, the processor begins executing at address 0, which is the Reset vector. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

The Wake-up Timer ensures that the oscillator and other analog functions required for chip operation are fully functional before the processor is allowed to execute instructions. This is important at power on, all types of Reset, and whenever any of the aforementioned functions are turned off for any reason. Since the oscillator and other functions are turned off during Power-down mode, any wake-up of the processor from Power-down mode makes use of the Wake-up Timer.

The Wake-up Timer monitors the crystal oscillator as the means of checking whether it is safe to begin code execution. When power is applied to the chip, or some event caused the chip to exit Power-down mode, some time is required for the oscillator to produce a signal of sufficient amplitude to drive the clock logic. The amount of time depends on many factors, including the rate of V_{DD} ramp (in the case of power on), the type of crystal and its electrical characteristics (if a quartz crystal is used), as well as any other external circuitry (e.g., capacitors), and the characteristics of the oscillator itself under the existing ambient conditions.

6.18.4 Code security (Code Read Protection - CRP)

This feature of the LPC2194/01 allows the user to enable different levels of security in the system so that access to the on-chip flash and use of the JTAG and ISP can be restricted. When needed, CRP is invoked by programming a specific pattern into a dedicated flash location. IAP commands are not affected by the CRP.

There are three levels of the Code Read Protection.

CRP1 disables access to chip via the JTAG and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors can not be erased.

CRP2 disables access to chip via the JTAG and only allows full flash erase and update using a reduced set of the ISP commands.

Running an application with level CRP3 selected fully disables any access to chip via the JTAG pins and the ISP. This mode effectively disables ISP override using P0[14] pin, too. It is up to the user's application to provide (if needed) flash update mechanism using IAP calls or call reinvoke ISP command to enable flash update via UART0.

when an application does not require any peripherals to run at the full processor rate. Because the APB divider is connected to the PLL output, the PLL remains active (if it was running) during Idle mode.

6.19 Emulation and debugging

The LPC2194 support emulation and debugging via a JTAG serial port. A trace port allows tracing program execution. Debugging and trace functions are multiplexed only with GPIOs on Port 1. This means that all communication, timer and interface peripherals residing on Port 0 are available during the development and debugging phase as they are when the application is run in the embedded system itself.

6.19.1 EmbeddedICE

Standard ARM EmbeddedICE logic provides on-chip debug support. The debugging of the target system requires a host computer running the debugger software and an EmbeddedICE protocol convertor. EmbeddedICE protocol convertor converts the Remote Debug Protocol commands to the JTAG data needed to access the ARM core.

The ARM core has a Debug Communication Channel function built-in. The debug communication channel allows a program running on the target to communicate with the host debugger or another separate host without stopping the program flow or even entering the debug state. The debug communication channel is accessed as a co-processor 14 by the program running on the ARM7TDMI-S core. The debug communication channel allows the JTAG port to be used for sending and receiving data without affecting the normal program flow. The debug communication channel data and control registers are mapped in to addresses in the EmbeddedICE logic.

The JTAG clock (TCK) must be slower than $\frac{1}{6}$ of the CPU clock (CCLK) for the JTAG interface to operate.

6.19.2 Embedded trace macrocell

Since the LPC2194 have significant amounts of on-chip memory, it is not possible to determine how the processor core is operating simply by observing the external pins. The Embedded Trace Macrocell (ETM) provides real-time trace capability for deeply embedded processor cores. It outputs information about processor execution to the trace port.

The ETM is connected directly to the ARM core and not to the main AMBA system bus. It compresses the trace information and exports it through a narrow trace port. An external trace port analyzer must capture the trace information under software debugger control. Instruction trace (or PC trace) shows the flow of execution of the processor and provides a list of all the instructions that were executed. Instruction trace is significantly compressed by only broadcasting branch addresses as well as a set of status signals that indicate the pipeline status on a cycle by cycle basis. Trace information generation can be controlled by selecting the trigger resource. Trigger resources include address comparators, counters and sequencers. Since trace information is compressed the software debugger requires a static image of the code being executed. Self-modifying code can not be traced because of this restriction.

6.19.3 RealMonitor

RealMonitor is a configurable software module, developed by ARM Inc., which enables real-time debug. It is a lightweight debug monitor that runs in the background while users debug their foreground application. It communicates with the host using the DCC (Debug Communications Channel), which is present in the EmbeddedICE logic. The LPC2194 contain a specific configuration of RealMonitor software programmed into the on-chip flash memory.

Table 5. Static characteristics *…continued*

T_{amb} = −40 °C to +125 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
Power consumption LPC2194							
$I_{DD(act)}$	active mode supply current	$V_{DD(1V8)}$ = 1.8 V; CCLK = 60 MHz; T_{amb} = 25 °C; code `while(1){}` executed from flash; all peripherals enabled via PCONP[11] register but not configured to run		-	60	-	mA
$I_{DD(pd)}$	Power-down mode supply current	$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 25 °C		-	10	-	µA
		$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 85 °C		-	110	500	µA
		$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 125 °C		-	300	1000	µA
Power consumption LPC2194/01							
$I_{DD(act)}$	active mode supply current	$V_{DD(1V8)}$ = 1.8 V; CCLK = 60 MHz; T_{amb} = 25 °C; code `while(1){}` executed from flash; all peripherals enabled via PCONP[11] register but not configured to run		-	43.5	-	mA
$I_{DD(idle)}$	Idle mode supply current	$V_{DD(1V8)}$ = 1.8 V; CCLK = 60 MHz; T_{amb} = 25 °C; executed from flash; all peripherals enabled via PCONP[11] register but not configured to run		-	11.5	-	mA
$I_{DD(pd)}$	Power-down mode supply current	$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 25 °C		-	10	-	µA
		$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 85 °C		-	110	500	µA
		$V_{DD(1V8)}$ = 1.8 V; T_{amb} = 125 °C		-	300	1000	µA
I^2C-bus pins							
V_{IH}	HIGH-level input voltage			$0.7V_{DD(3V3)}$	-	-	V
V_{IL}	LOW-level input voltage			-	-	$0.3V_{DD(3V3)}$	V
V_{hys}	hysteresis voltage			-	$0.05V_{DD(3V3)}$	-	V
V_{OL}	LOW-level output voltage	I_{OLS} = 3 mA	[7]	-	-	0.4	V
I_{LI}	input leakage current	$V_I = V_{DD(3V3)}$	[12]	-	2	4	µA
		V_I = 5 V		-	10	22	µA

Table 5. Static characteristics *…continued*

T_{amb} = −40 °C to +125 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
Oscillator pins						
$V_{i(XTAL1)}$	input voltage on pin XTAL1		0	-	1.8	V
$V_{o(XTAL2)}$	output voltage on pin XTAL2		0	-	1.8	V

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] Internal rail.

[3] External rail.

[4] Including voltage on outputs in 3-state mode.

[5] $V_{DD(3V3)}$ supply voltages must be present.

[6] 3-state outputs go into 3-state mode when $V_{DD(3V3)}$ is grounded.

[7] Accounts for 100 mV voltage drop in all supply lines.

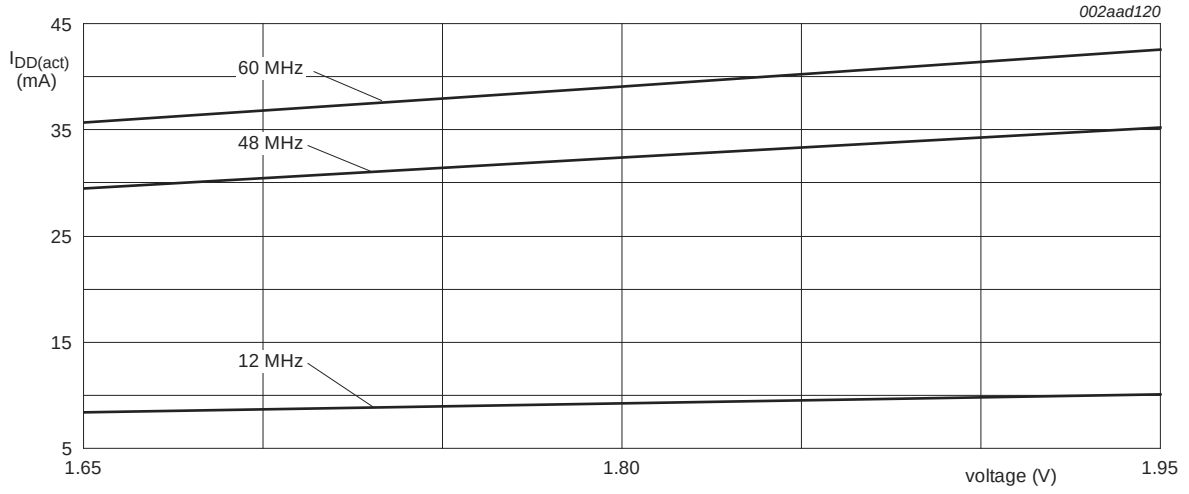
[8] Only allowed for a short time period.

[9] Minimum condition for V_I = 4.5 V, maximum condition for V_I = 5.5 V.

[10] Applies to P1[25:16].

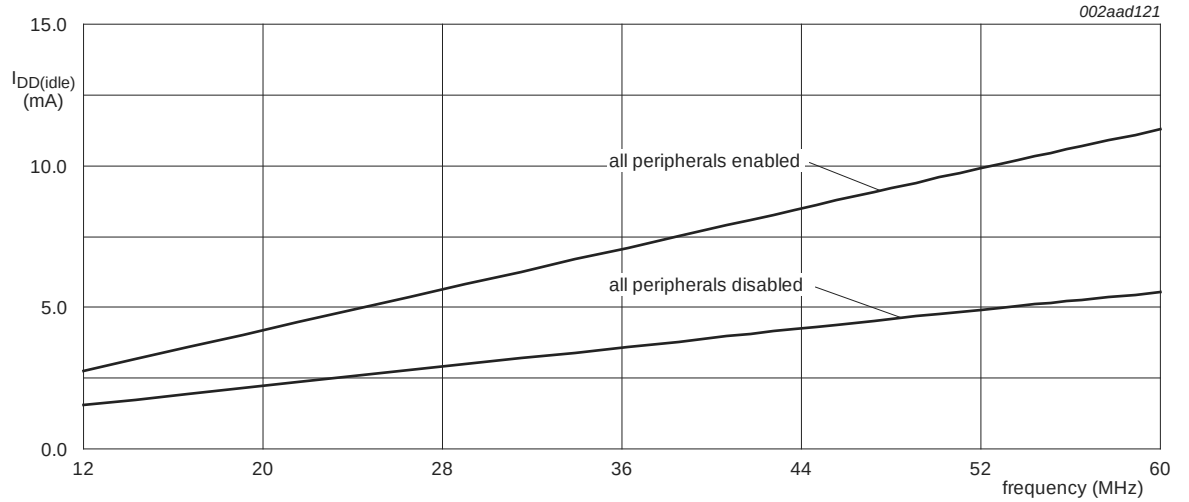
[11] See *LPC2119/2129/2194/2292/2294 User Manual*.

[12] To V_{SS}.



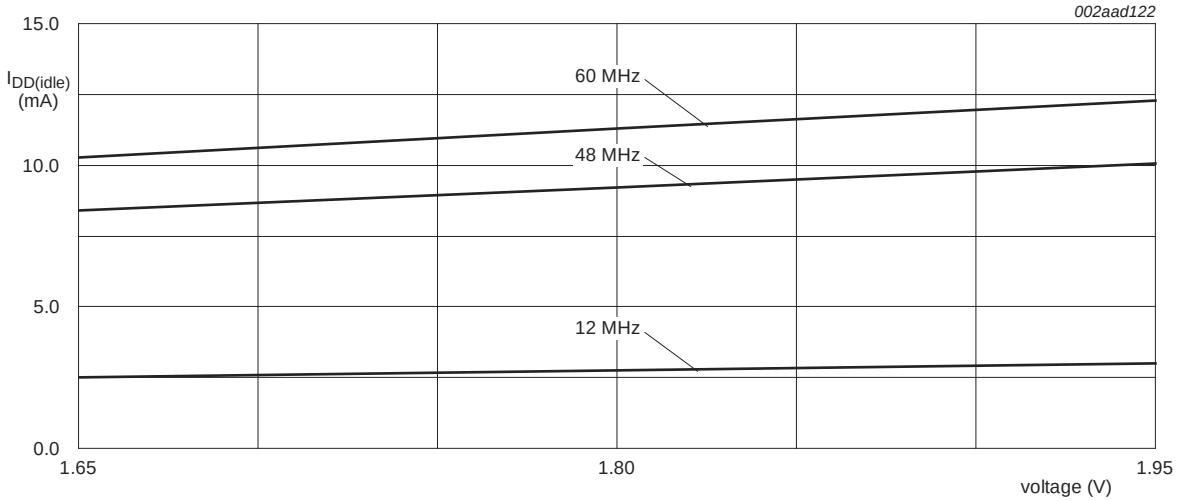
Test conditions: Active mode entered executing code from on-chip flash; PCLK = $^{CCLK}/_{4}$;
Temp = 25 °C; core voltage 1.8 V; all peripherals disabled.

Fig 7. Typical LPC2194/01 $I_{DD(act)}$ measured at different voltages



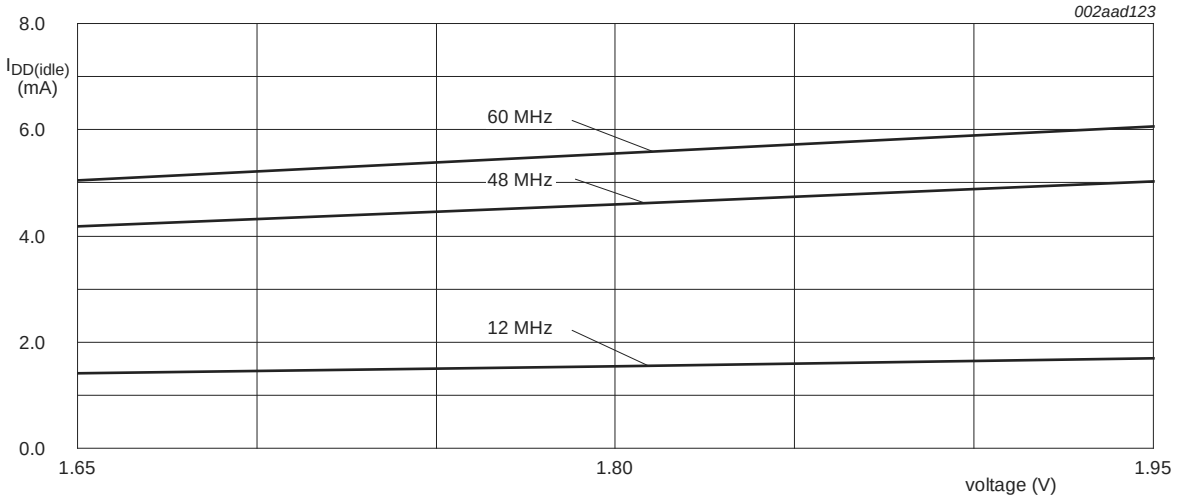
Test conditions: Idle mode entered executing code from on-chip flash; PCLK = $^{CCLK}/_{4}$;
T_{amb} = 25 °C; core voltage 1.8 V.

Fig 8. Typical LPC2194/01 $I_{DD(idle)}$ measured at different frequencies



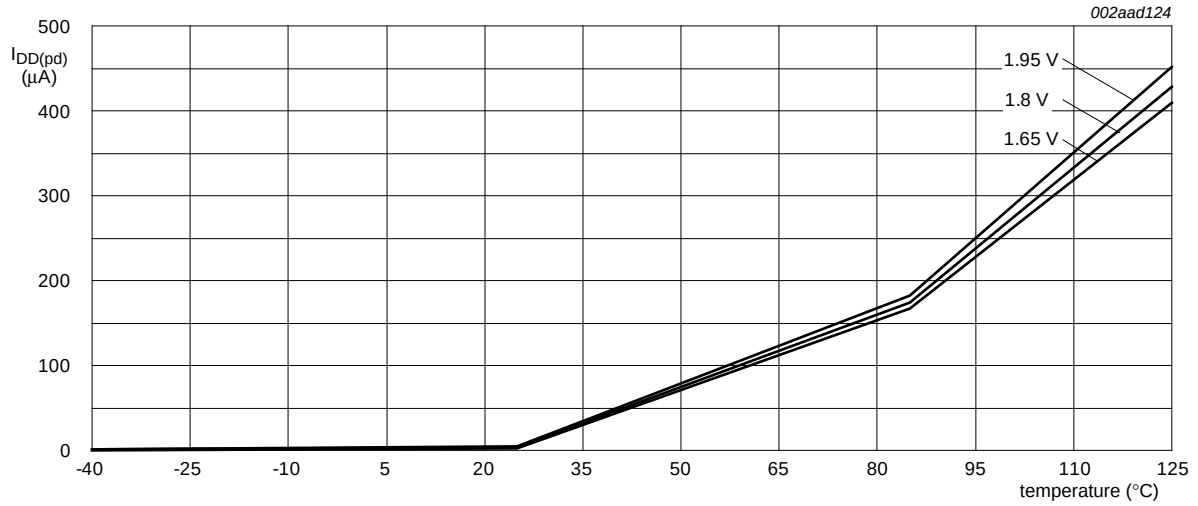
Test conditions: Idle mode entered executing code from on-chip flash; PCLK = $^{CCLK}/_{4}$;
T_{amb} = 25 °C; core voltage 1.8 V; all peripherals enabled.

Fig 9. Typical LPC2194/01 $I_{DD(idle)}$ measured at different voltages



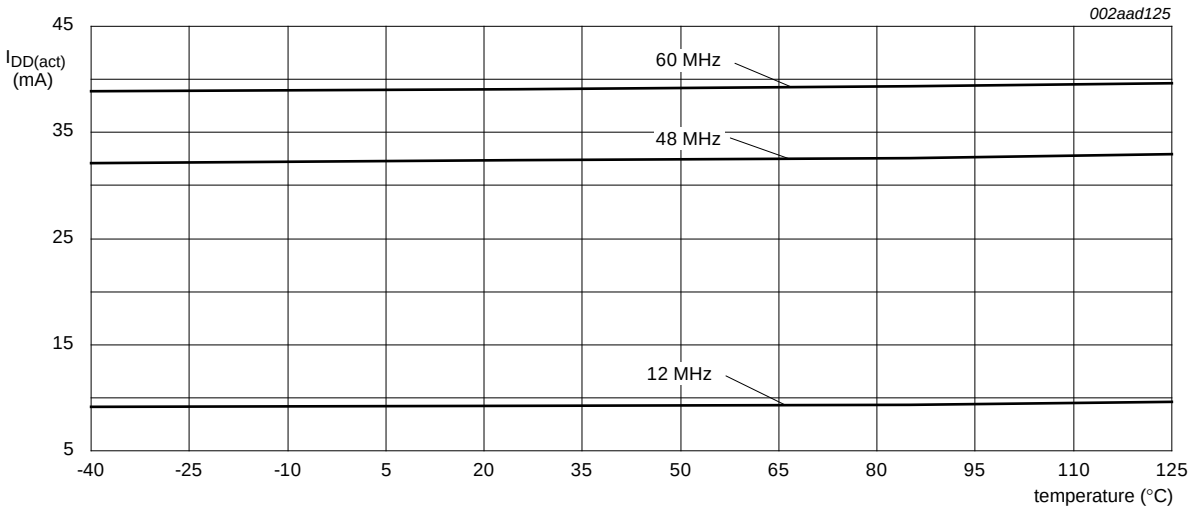
Test conditions: Idle mode entered executing code from on-chip flash; PCLK = $^{CCLK}/_{4}$;
Temp = 25 °C; core voltage 1.8 V; all peripherals disabled.

Fig 10. Typical LPC2194/01 $I_{DD(idle)}$ measured at different voltages



Test conditions: Power-down mode entered executing code from on-chip flash.

Fig 11. Typical LPC2194/01 core power-down current $I_{DD(pd)}$ measured at different temperatures

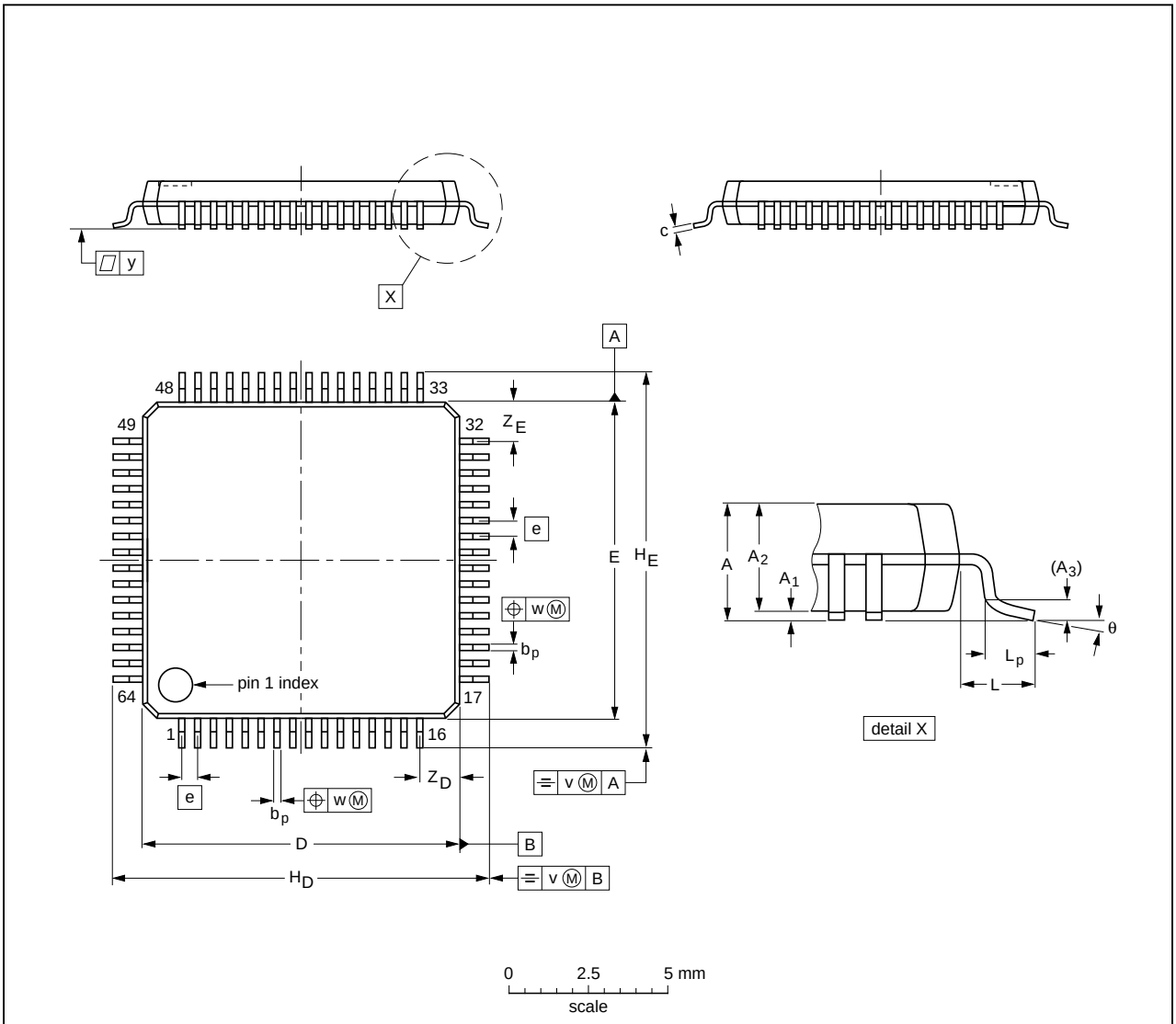


Test conditions: code executed from on-chip flash; PCLK = $^{CCLK}/_{4}$;
core voltage 1.8 V; all peripherals disabled.

Fig 12. Typical LPC2194/01 $I_{DD(act)}$ measured at different temperatures

10. Package outline

LQFP64: plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm **SOT314-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	10.1 9.9	10.1 9.9	0.5	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.12	0.1	1.45 1.05	1.45 1.05	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT314-2	136E10	MS-026				~~00-01-19~~ 03-02-25

Fig 15. Package outline SOT314-2 (LQFP64)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC2194 v.6	20110614	Product data sheet	201004021F	LPC2194 v.5
Modifications:	• Table 5 “Static characteristics”; Changed /01 Power-down mode supply current ($I_{DD(pd)}$) from 180 μA to 500 μA for industrial temperature range, and 430 μA to 1000 μA for extended temperature range. • Table 5 “Static characteristics”; Moved V_{hys} voltage from typical to minimum. • Table 5 “Static characteristics”; Changed I^2C pad hysteresis from $0.5V_{DD(3V3)}$ to $0.05V_{DD(3V3)}$.			
LPC2194 v.5	20071210	Product data sheet	-	LPC2194 v.4
Modifications:	• Type number LPC2194HBD64/01 has been added. • Details introduced with /01 devices on new peripherals/features (Fast I/O Ports, SSP, CRP) and enhancements to existing ones (UART0/1, Timers, ADC, and SPI) added. • Power consumption measurements for LPC2194/01 added. • Description of JTAG pin TCK has been updated.			
LPC2194 v.4	20061016	Product data sheet	-	LPC2194 v.3
LPC2194 v.3	20060714	Product data sheet	-	LPC2194 v.2
LPC2194 v.2	20041222	Product data	-	LPC2194 v.1
LPC2194 v.1	20040206	Preliminary data	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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